

 $\begin{array}{cccc} R & & \vdots & & A0 \\ C & & N \ . \vdots & & \end{array}$

Revision Record					
Control No.	Revision	Description	Date	Drawn	Approved

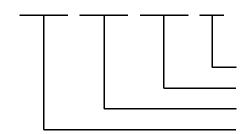
 $\begin{array}{ccc} R & & \vdots \\ C & & N \ . \vdots \end{array}$ A0

TMAX-1770-XXX-M M lded P e I d c

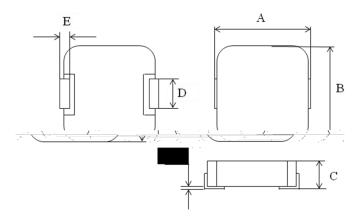
Features

Applications

Product Description



Dimensions

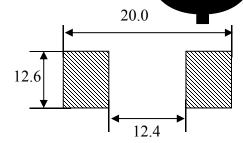


17.5 Max.
17.15 Max.
7.0 Max.
11.8±0.3
2.5±0.5
0~0.30



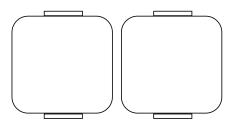
R A0

Recommend Lan Par err Timensions

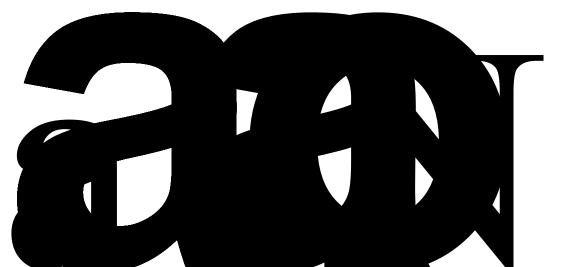


Marking

•



I a : 0.1 H



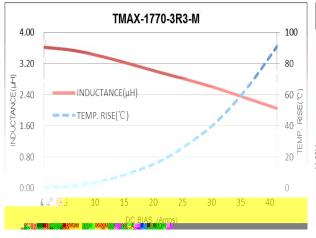
2

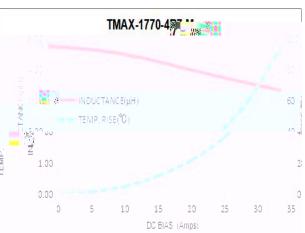
R : A0 C N ::

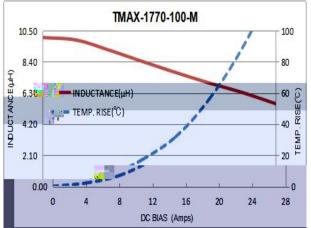
Notes:

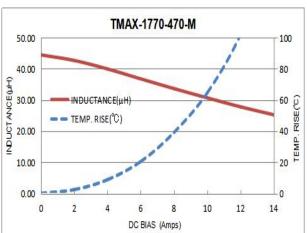
: (),

Inductance and Temperature Rise vs. DC Current



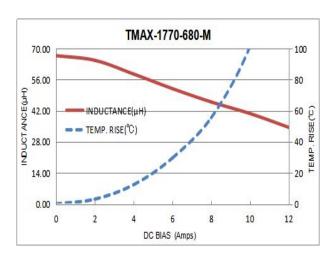








R C A0 N .:



Reliability:

Item	Test Method	Specification and Requirement
	± ± °C ±	
		±

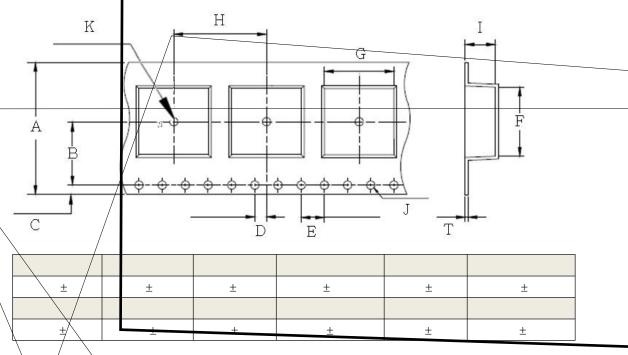


Reliability:

Item	Test Method	Specification and Requirement
	$\begin{array}{cccccccccccccccccccccccccccccccccccc$	
	±	±
	±	
	±	
	±	



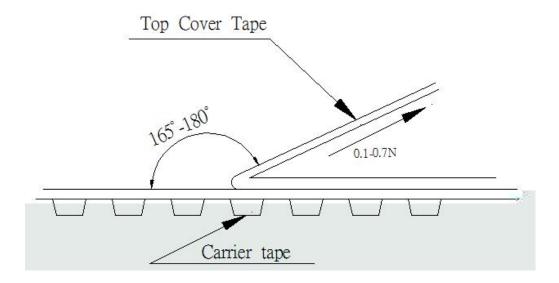
Packaging Dimensions





1	1	
工	エ	

Peeling of top cover tape





R A0 C $N \mathrel{\dot{.}\dot{.}}$

Reflow Profile

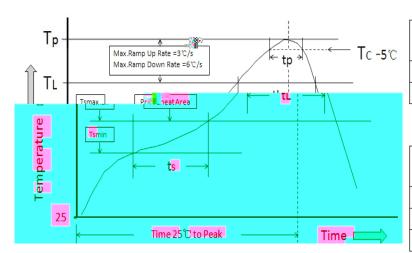


Table1-StandardSnPb Solder(Tc)

Package Thickness	Volume mm³ <350	Volume mm³ ≧350
<	$^{\circ}$	$^{\circ}$
≧	°C	°C

Table2-Lead(Pb)Free Solder(Tc)

Package Thickness	Volume mm³ <350	Volume mm³ 350-2000	Volume mm³ >2000
<	$^{\circ}$ C	℃	°C
	$^{\circ}$	℃	$^{\circ}$
	$^{\circ}$	°C	°C

Reference JDEC J-STD-020(latest revision)

Profile Feature	Standard SnPb sold	er Lead(Pb) Free Solder
	°C	${\mathbb C}$
	°C	${\mathbb C}$
	$^{\circ}$ C	$^{\circ}$
	°C	$^{\circ}\mathbb{C}$
${}^{\sim}$		
	°C	°C
${}^{\mathbb{C}}$		



 $\begin{array}{cccc} R & & \vdots & & A0 \\ C & & N \ . \vdots & & \end{array}$

Numbers of taping

Label marking

Production Label

Shipping Label

Care note for use

> Storage Condition

> Use Temperature



R : A0 C N .:

Care note for Safety